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# Geiger mode avalanche photodiodes in particle detection

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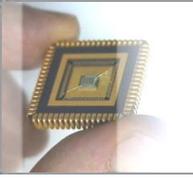
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## ➤ Outline

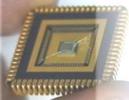
### ➤ **Introduction**

- Our GAPDs timeline
- Available technologies
- Test beam program

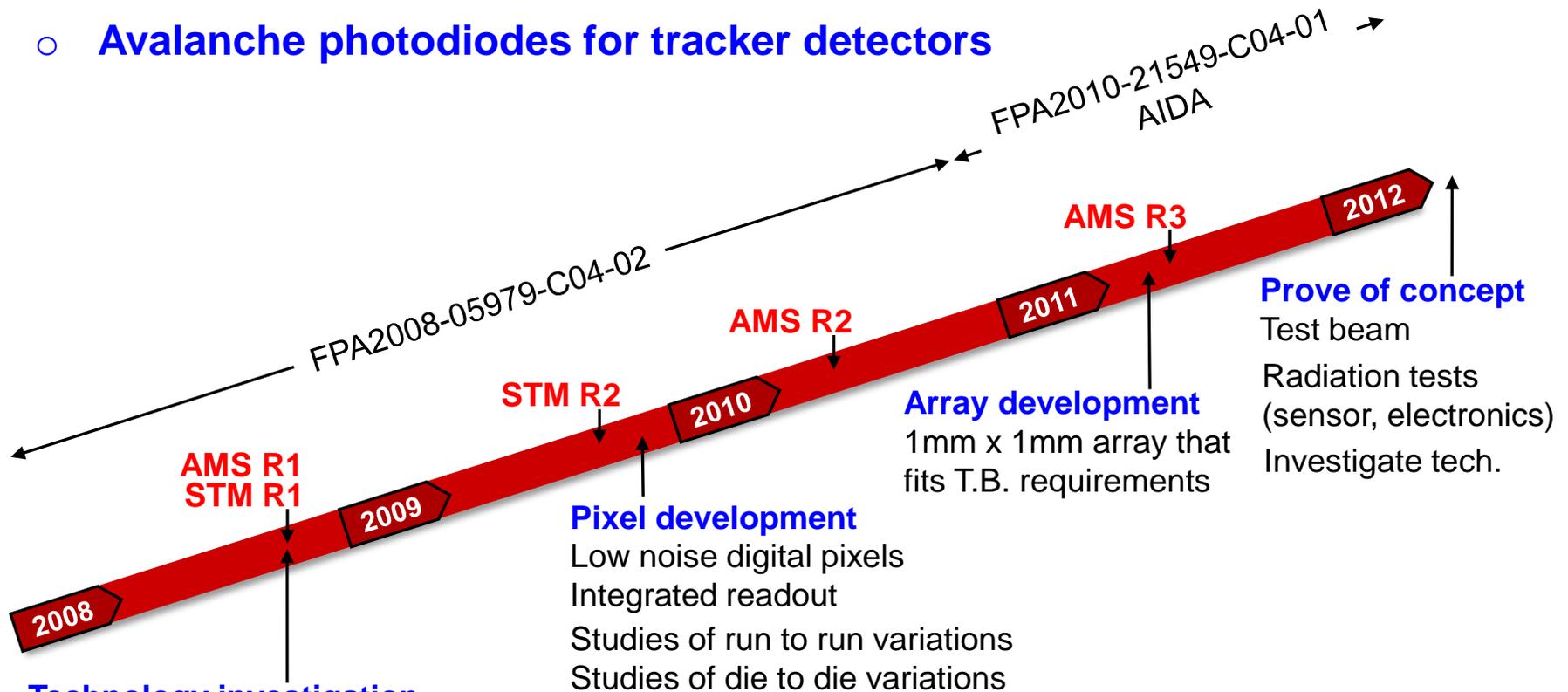
### ➤ **1mm x 1mm GAPD array**

- FLC\_APD\_v1
- Pixel schematic
- Gated operation
- Results

### ➤ **Conclusions**



## ○ Avalanche photodiodes for tracker detectors



### Technology investigation

- Technology exploration (STM, HV-AMS)
- Analyses of structures (STI)
- Sensor characterization (I(V), noise, dynamic behavior & range)
- Studies of sensitive area with FIB

### Pixel development

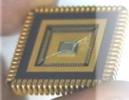
- Low noise digital pixels
- Integrated readout
- Studies of run to run variations
- Studies of die to die variations

### Array development

- 1mm x 1mm array that fits T.B. requirements

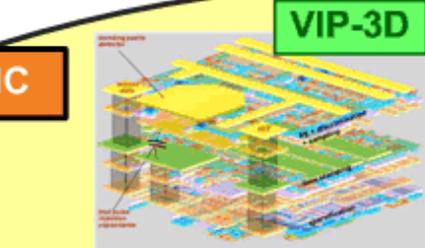
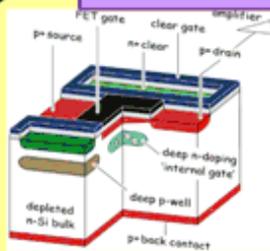
### Prove of concept

- Test beam
- Radiation tests (sensor, electronics)
- Investigate tech.

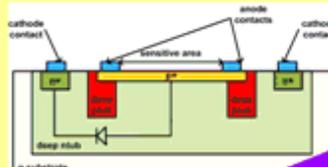


## MONOLITHIC

### DEPFETs

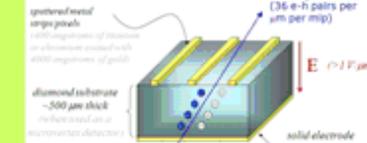
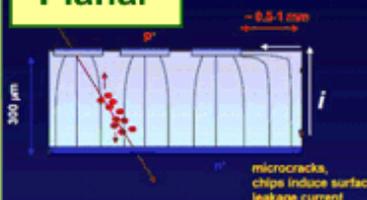


### VIP-3D



### GAPD

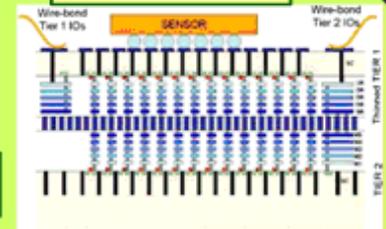
## Planar



### Diamond

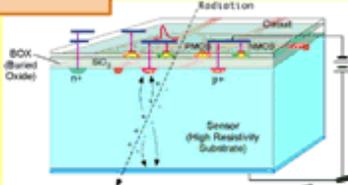
## HYBRID

### Hybrid-3D

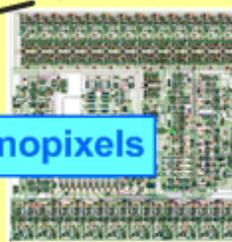


# Pixel technologies

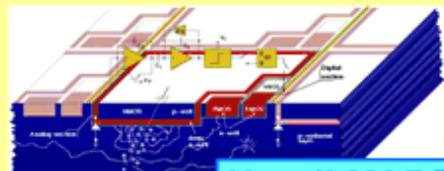
## SOI-3D



## chronopixels

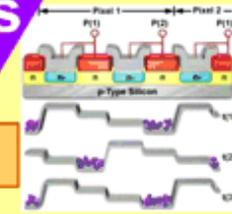


### MAPS

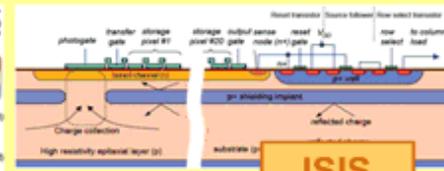
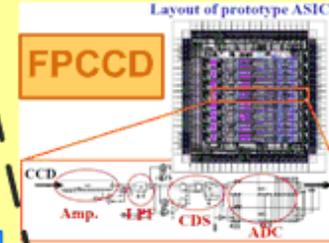


### N-well MAPS

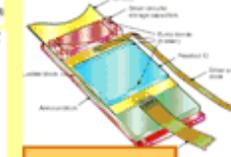
## CCD



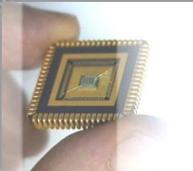
## FPCCD



### ISIS



### CPCCD



## ○ Geiger mode Avalanche Photodiodes (GAPDs)

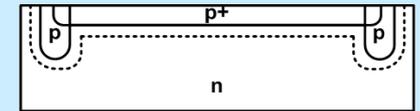
### • Pros

- ✓ High intrinsic gain (no amplifier is needed)
- ✓ Accurate time response (possible single BX detection)
- ✓ Compatible with standard CMOS processes

### • Cons

- x Afterpulses
  - x Dark counts
  - x Crosstalk
- } → Noise counts, indistinguishable from real **events**
- x Reduction of detector performance
  - x Increase of memory area to store the total hits

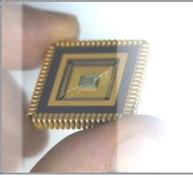
Avalanche photodiodes in standard CMOS technologies



## ○ It is mandatory to reduce noise counts! How?

- Through technology
- Introducing readout electronics for low noise GAPD pixels

*E. Vitella*



## ○ Intrinsic noise sources

### • Dark counts

- Spurious pulses due to thermal and tunneling carriers generated within the p-n junction.
- Depends on the doping profile (technology), quality of the process (sensor area), reverse bias overvoltage and temperature.
- Measured in terms of frequency of generation or dark count rate (DCR). Typical values range from Hz to hundreds of kHz.

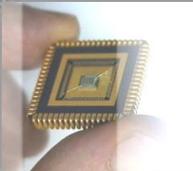
### ○ Afterpulses

- Correlated pulses due to charge carriers trapped during a previous avalanche and released some time later.
- Depends on the trap density, the number of carriers generated during an avalanche and the lifetime of these carriers.

### ○ Crosstalk

- Spurious pulses caused by interactions among adjacent pixels (electrical) or photons generated during an avalanche in a neighbouring pixel (optical).
- Depends on the sensor pitch, the number of carriers generated in an avalanche and the reverse bias overvoltage.

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## ○ We plan to go to 2 test beams

1) **DESY (2011)** - Initial test beam with 6GeV electrons

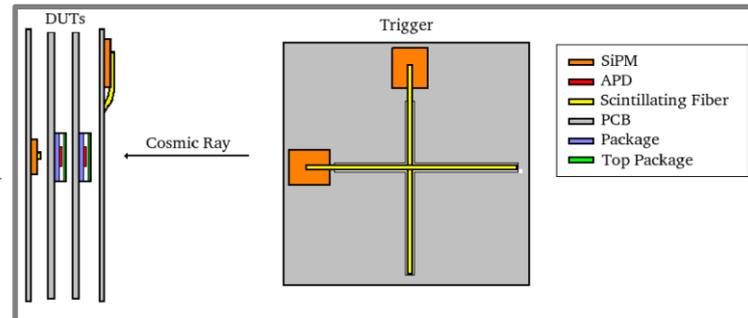
We expect to distinguish detection between neighbour pixels

2) **CERN (2012)** - Final test beam with 120GeV pions

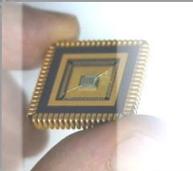
We expect to distinguish detection in an specific region of the pixel

## ○ Test set-up

- DUT (1mm x 1mm GAPD array), PCB, scintillators and telescope (EUDET)
- A TLU is used to distribute the trigger
- Main worries → Hit density losses with distance and distortion in the particle path caused by test set-up materials
- Different ideas to reduce total material thickness
  - GAPD array with thin silicon wafer of 250µm
  - No chip package & wire bond the chip directly to the PCB
  - PCB perforated under the chip
- Running simulations with **Geant4**
  - Software to simulate the passage of particles through matter

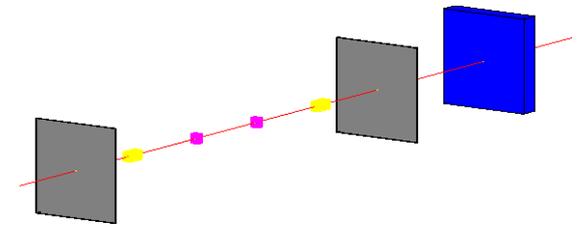


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## Geant4 studies

- Performed using 2 silicon wafers, 2 aluminum layers and 2 or 4 scintillators (test beam set-up)
- Sources → electrons (6GeV) and pions (120GeV)



## Results

	Detector at 2cm	X-Mean ( $\mu\text{m}$ )	X-Sigma ( $\mu\text{m}$ )	Y-Mean ( $\mu\text{m}$ )	Y-Sigma ( $\mu\text{m}$ )	Peak ( $\mu\text{m}$ )	R-Sigma ( $\mu\text{m}$ )
electrons	T.B. with 2 Sc.	-0.0801	16.2	0.008922	16.2	13	12.48
	T.B. with 4 Sc.	0.1474	17.6	0.07584	17.68	13	13.34
pions	T.B. with 2 Sc.	0.008092	0.7767	0.001725	0.7814	0.7	0.5769
	T.B. with 4 Sc.	0.0001457	0.8606	0.003204	0.8625	0.8	0.6955

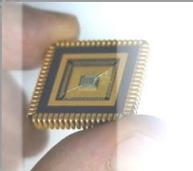
  

	Detector at 10cm	X-Mean ( $\mu\text{m}$ )	X-Sigma ( $\mu\text{m}$ )	Y-Mean ( $\mu\text{m}$ )	Y-Sigma ( $\mu\text{m}$ )	Peak ( $\mu\text{m}$ )	R-Sigma ( $\mu\text{m}$ )
electrons	T.B. with 2 Sc.	-0.2033	16.91	0.18	46.88	35	39.25
	T.B. with 4 Sc.	0.3413	50.18	-0.06107	50.39	37	41.75
pions	T.B. with 2 Sc.	0.004929	2.092	0.00374	2.1	1.8	1.614
	T.B. with 4 Sc.	0.000984	2.301	0.00865	2.308	1.9	1.749

## We need distortion lower than pixel width (20 $\mu\text{m}$ )!

- T.B. at DESY (electrons) → distortion is  $\sim 16\mu\text{m}$
- Complicated to characterize (further studies are needed)
- T.B. at CERN (pions) → distortion is  $\sim 0.5\mu\text{m}$
- To measure detector resolution and active regions we need 1-2 $\mu\text{m}$  precision

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## ○ Aim of the chip

- **Characterize GAPDs response to MIPs in a test beam**

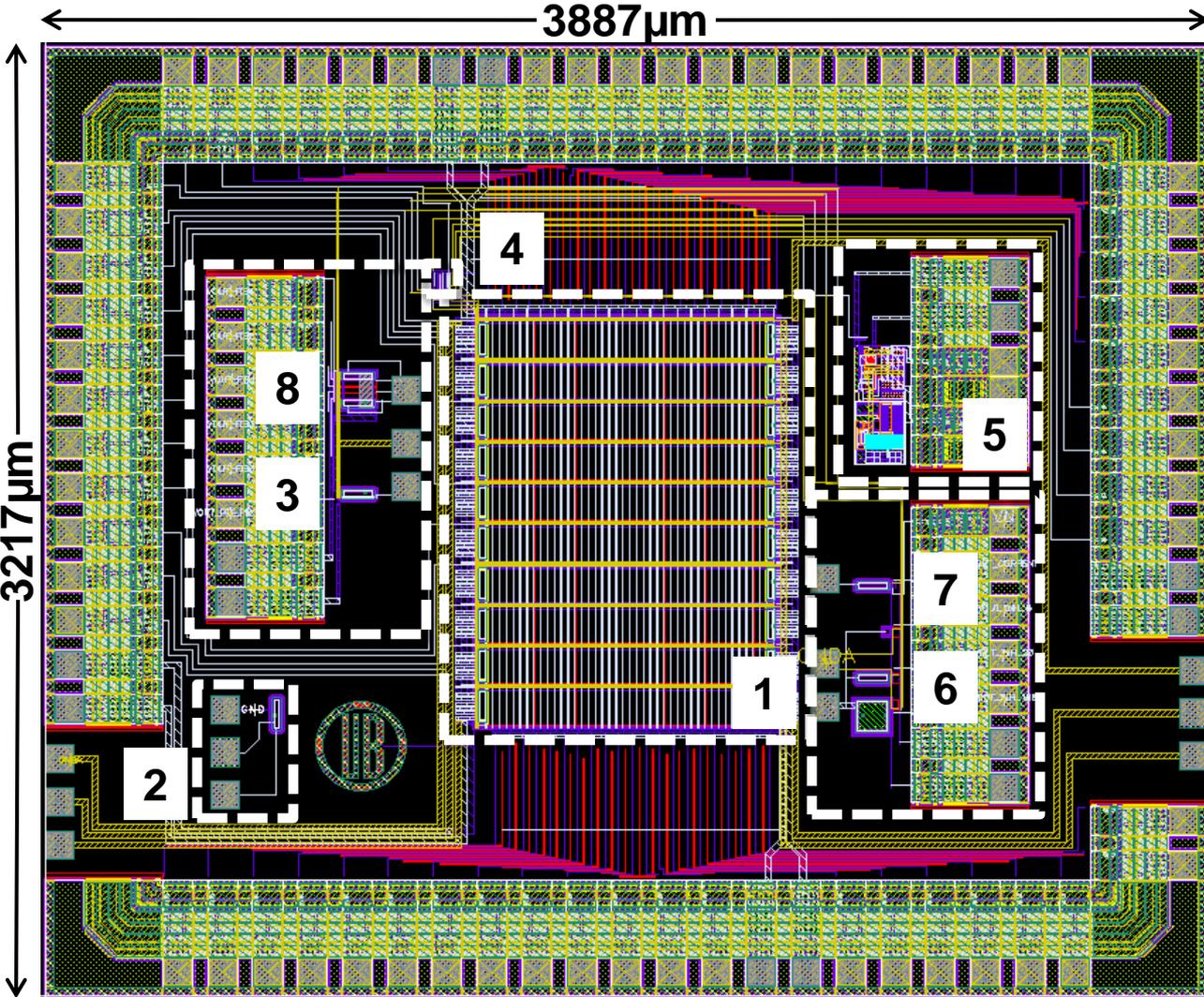
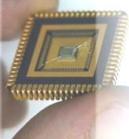
- Measurements of efficiency depending on position and time
- Study the areas of sensitivity
- Crosstalk characterization

## ○ Requirements

- Minimum sensitive area is 1mm x 1mm
- Sensor area is 20 $\mu$ m x 100 $\mu$ m (optimized for ILC forward tracking)

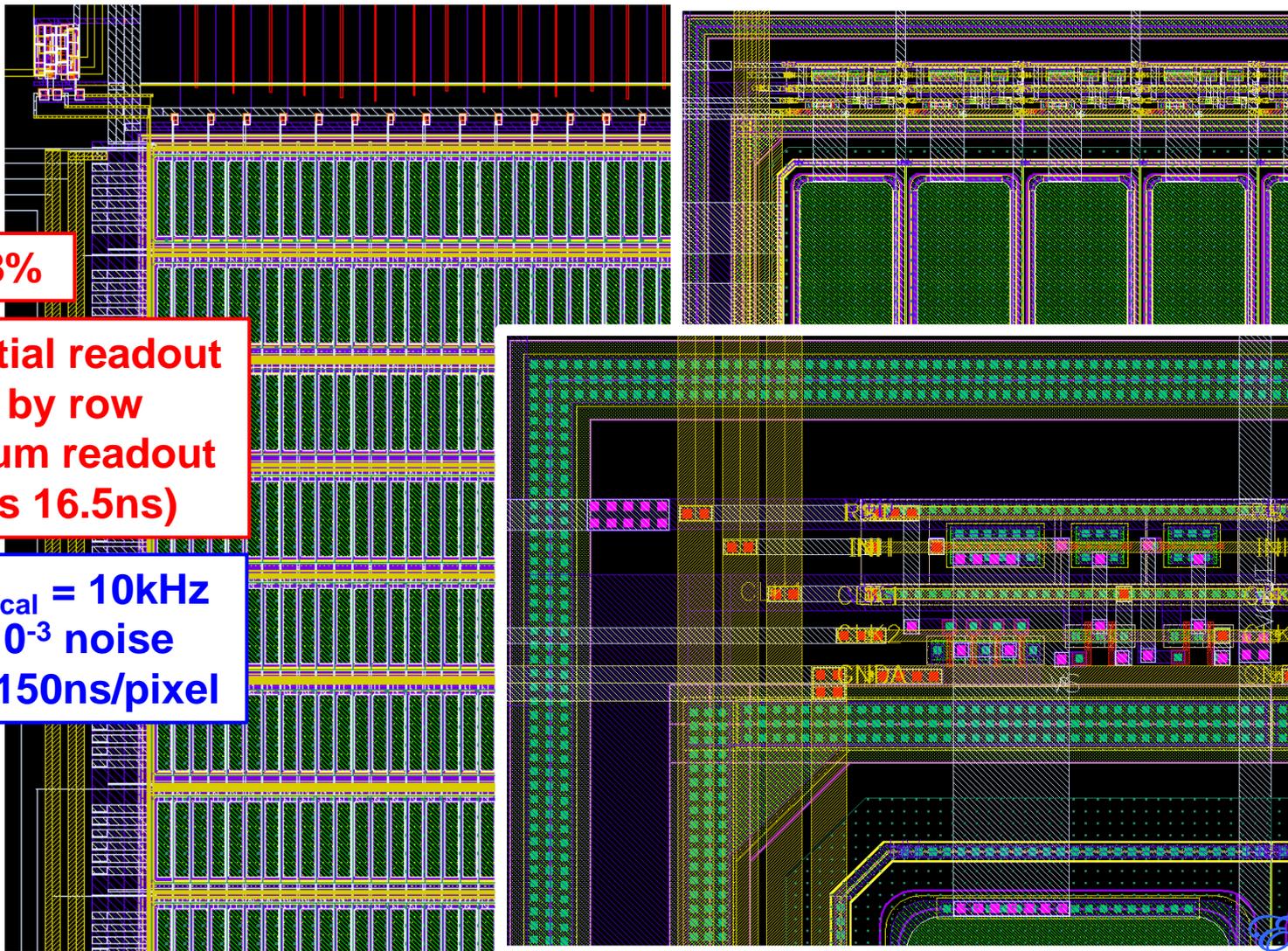
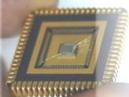
## ○ Not taken into account (by now)

- Fill factor (FF)
- Radiation tolerance
- Use the best technology in terms of FF, speed, noise and cost



- 1. 10 x 43 GAPD array
- 2. Test photodiode
- 3. Test pixel
- 4. Control signal generation circuit
- 5. Pad LVDS
- 6. Active inhibit pixel
- 7. Current mode pixel
- 8. 1 x 5 GAPD array with PAD layer

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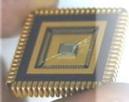


**FF is 88%**

**Sequential readout  
row by row  
(minimum readout  
time is 16.5ns)**

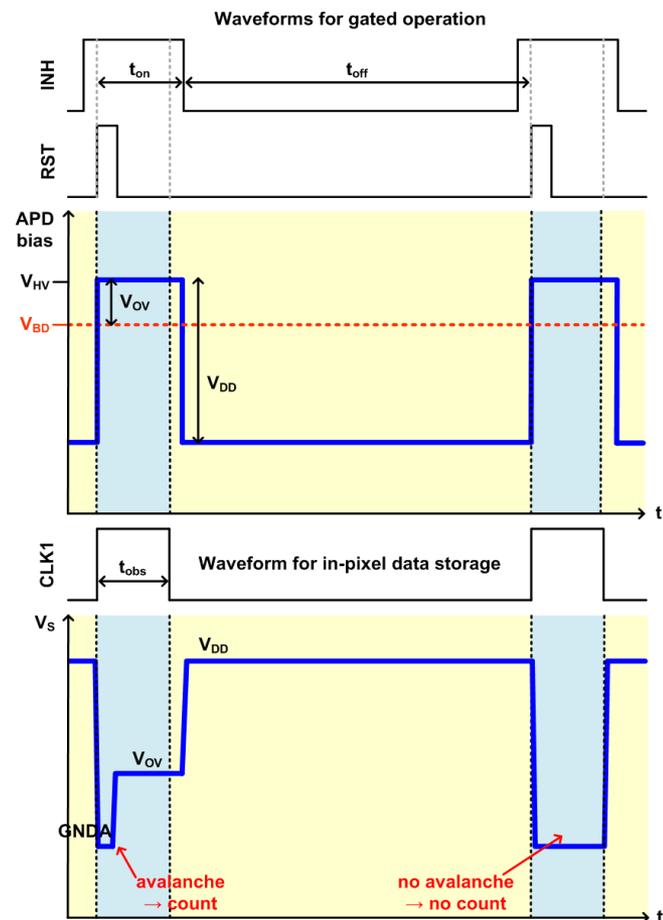
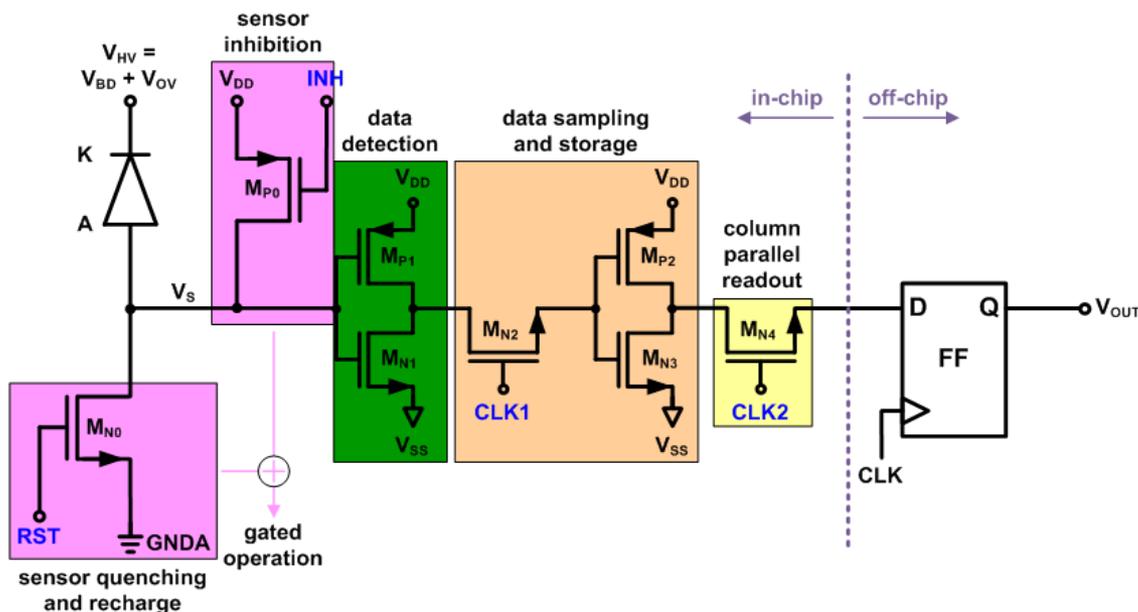
**DCR<sub>Typical</sub> = 10kHz  
→ 1·10<sup>-3</sup> noise  
counts/150ns/pixel**

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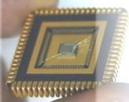


Pixel schematic and mode of operation

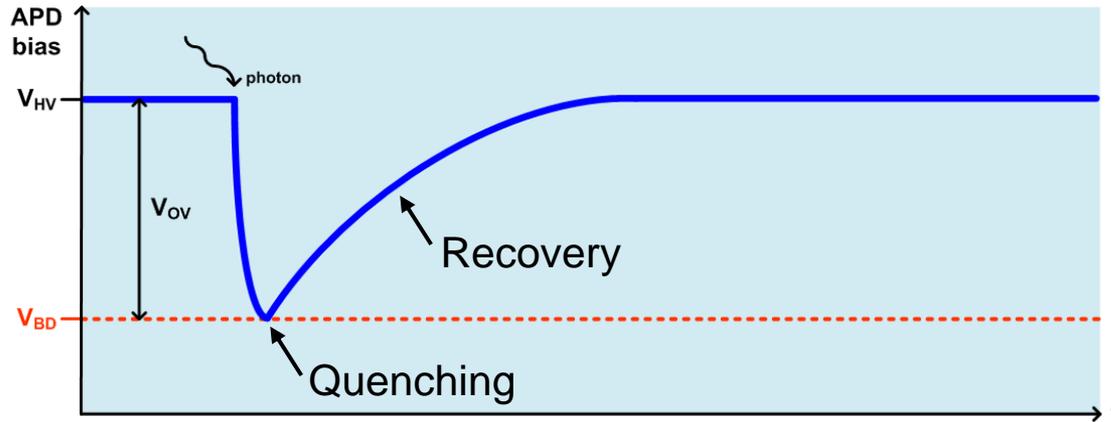
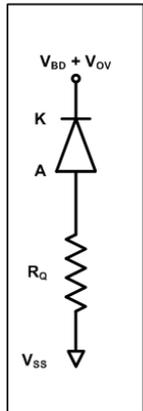
- Sensor and readout electronics monolithically integrated in the same die.
- Noise reduction through readout electronics (readout circuit for low overvoltage and gated operation).
- Digital output.



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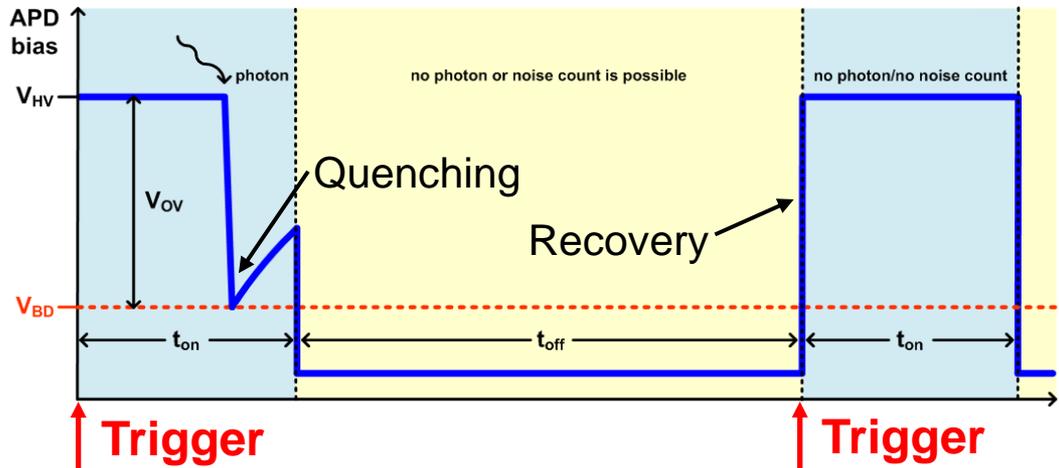
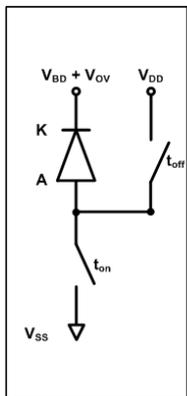


## Free running



The APD is always active.

## Gated operation

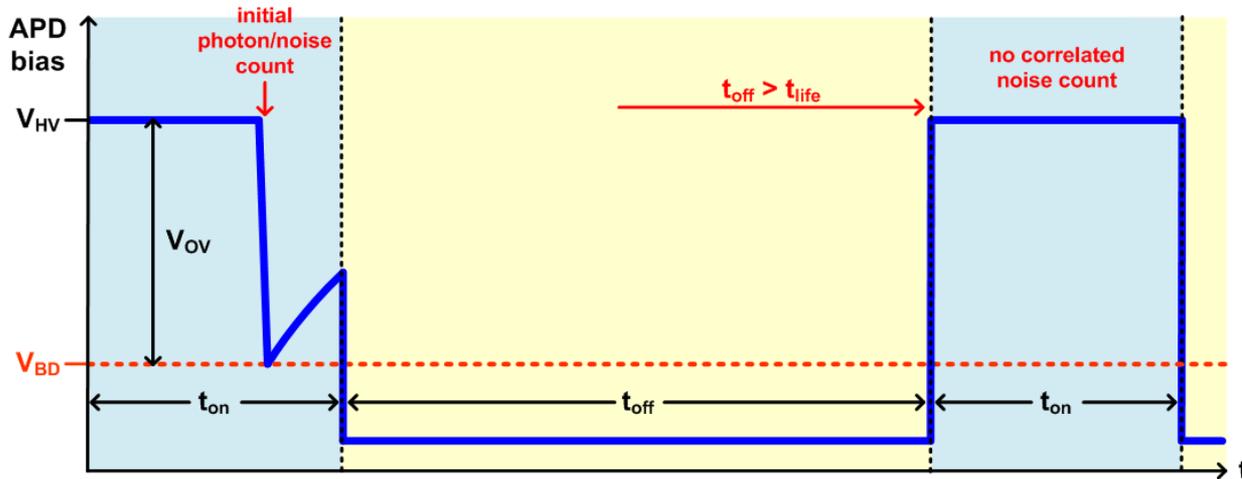
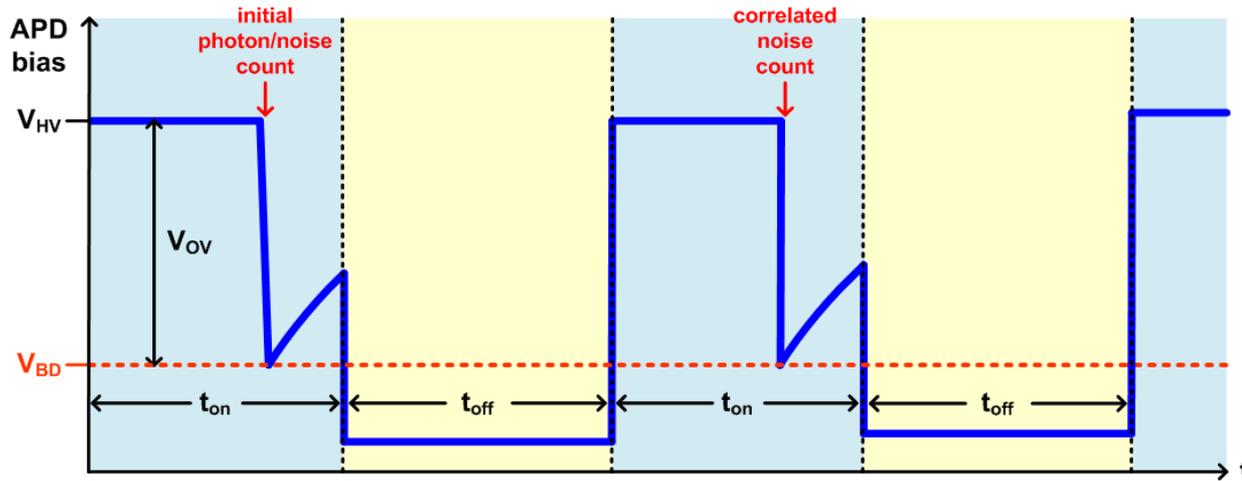
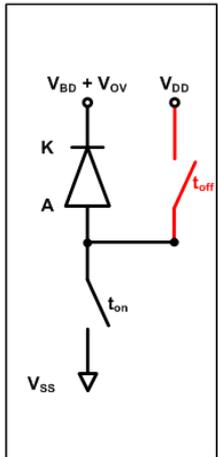


The APD is active for short  $t_{on}$  by using a triggering signal.

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## Gated operation



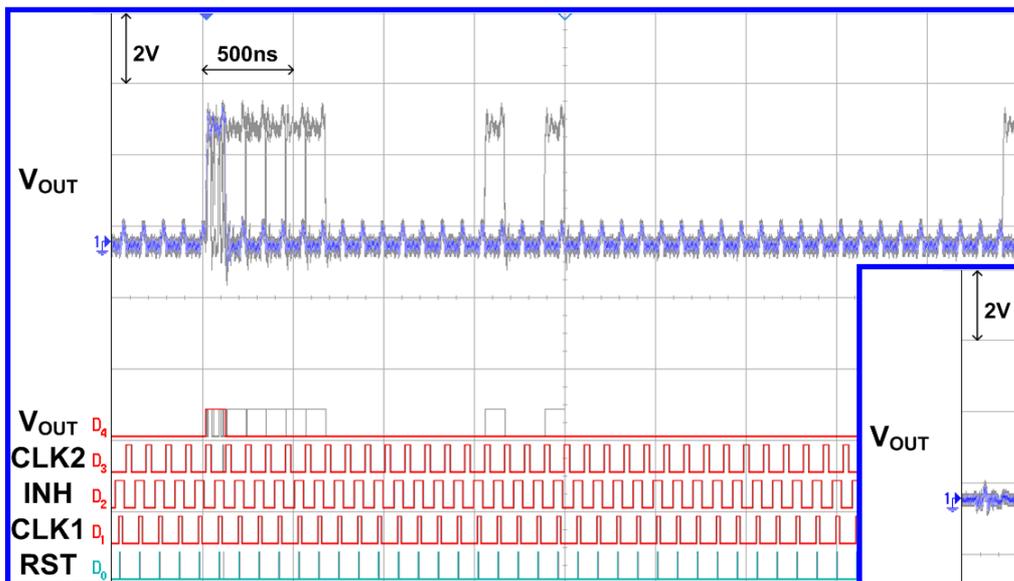
Avoids  
afterpulses  
with  
 $t_{off} > t_{life}$   
of trap  
carriers

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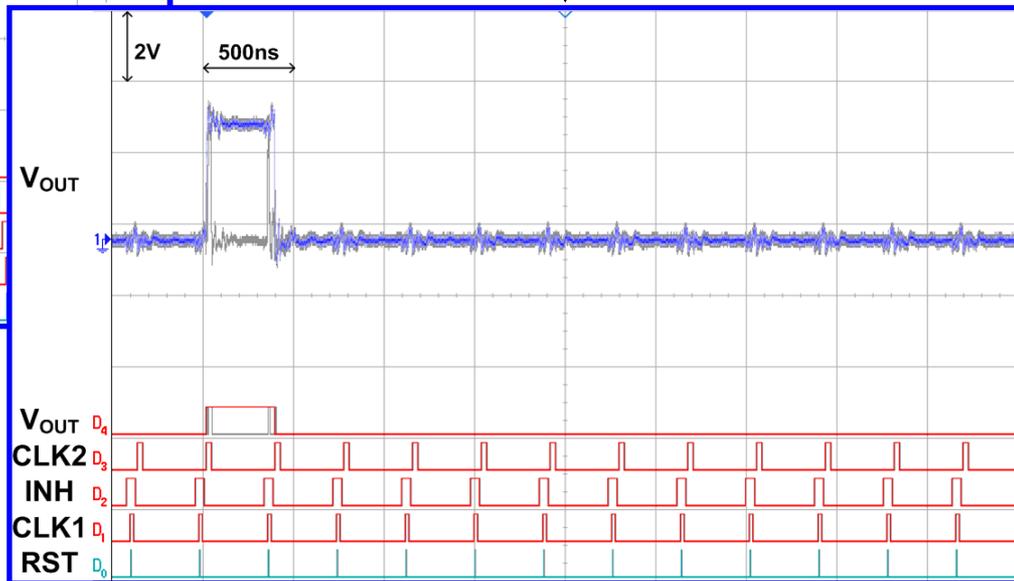
○ It is possible to eliminate the afterpulsing probability by means of the gated operation.

- Leaving long enough  $t_{off}$  periods of 300ns.



$t_{off} = 80ns$

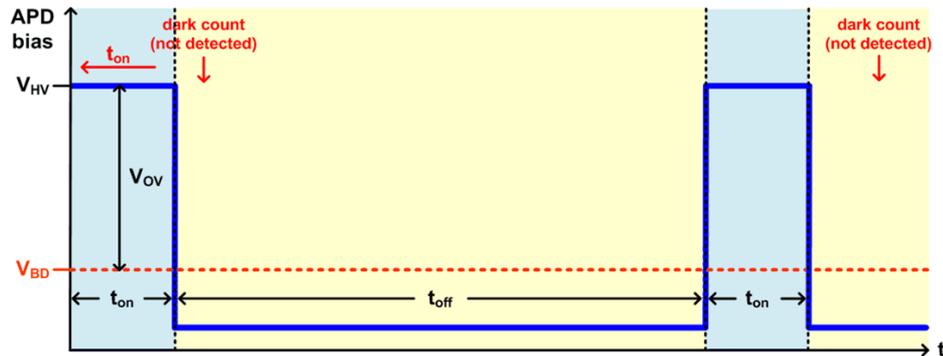
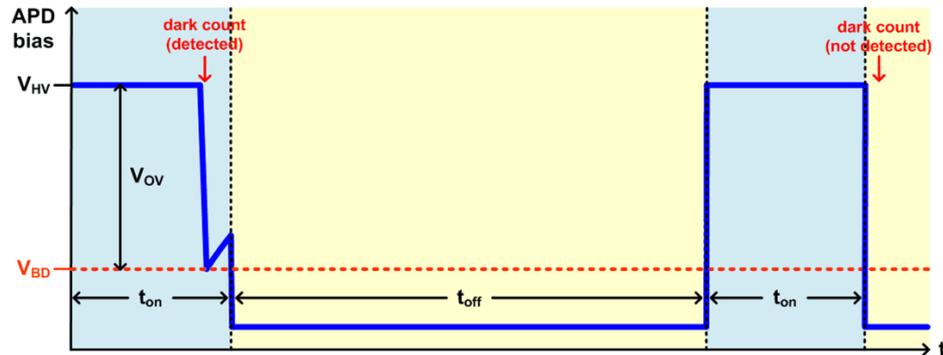
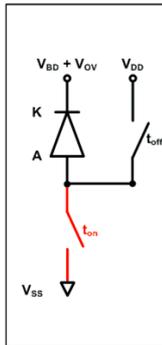
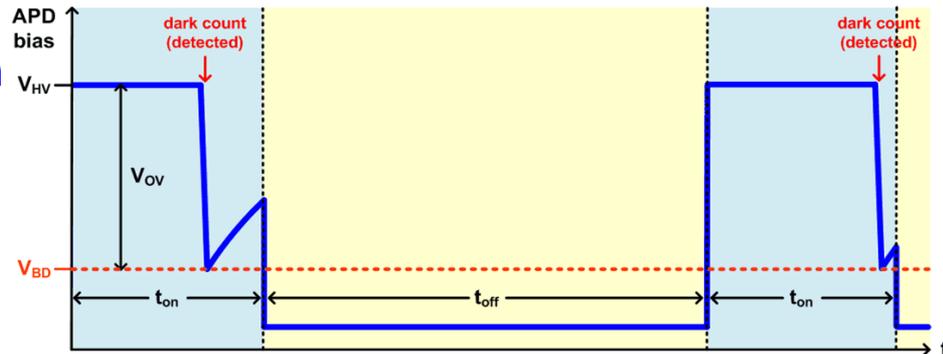
$t_{off} = 300ns$



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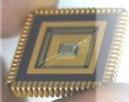


## Gated operation

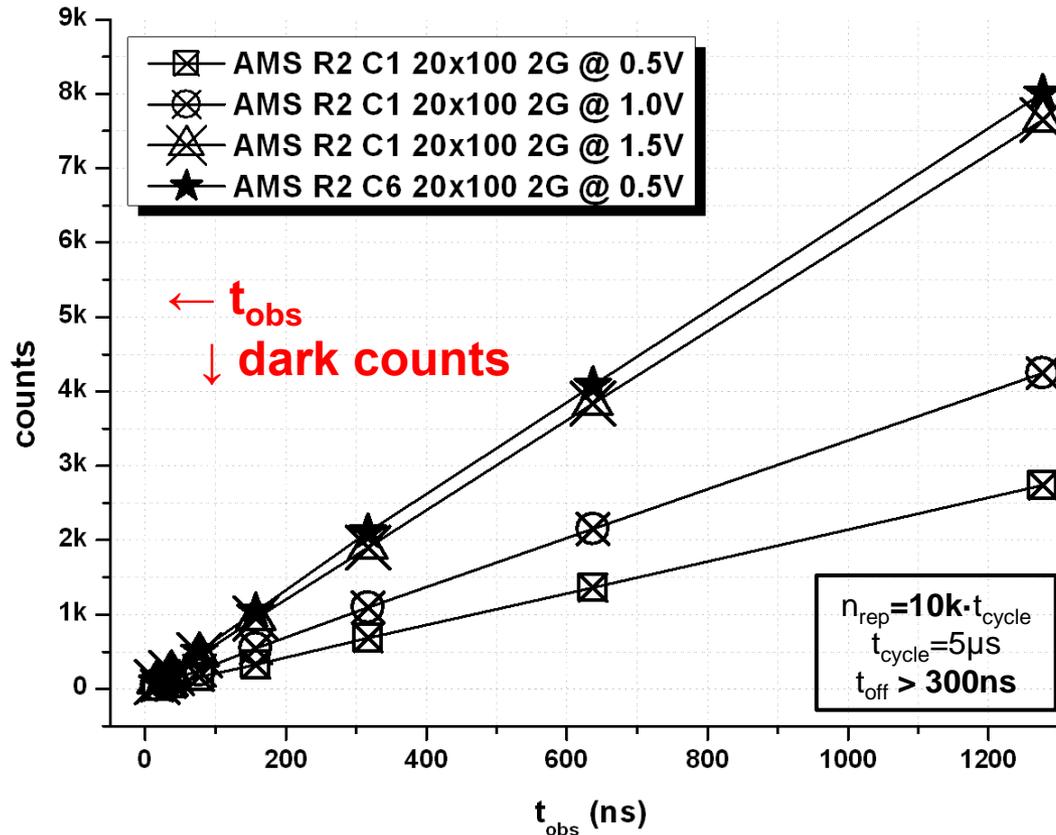


Reduces the probability to detect a dark count with short  $t_{on}$ .

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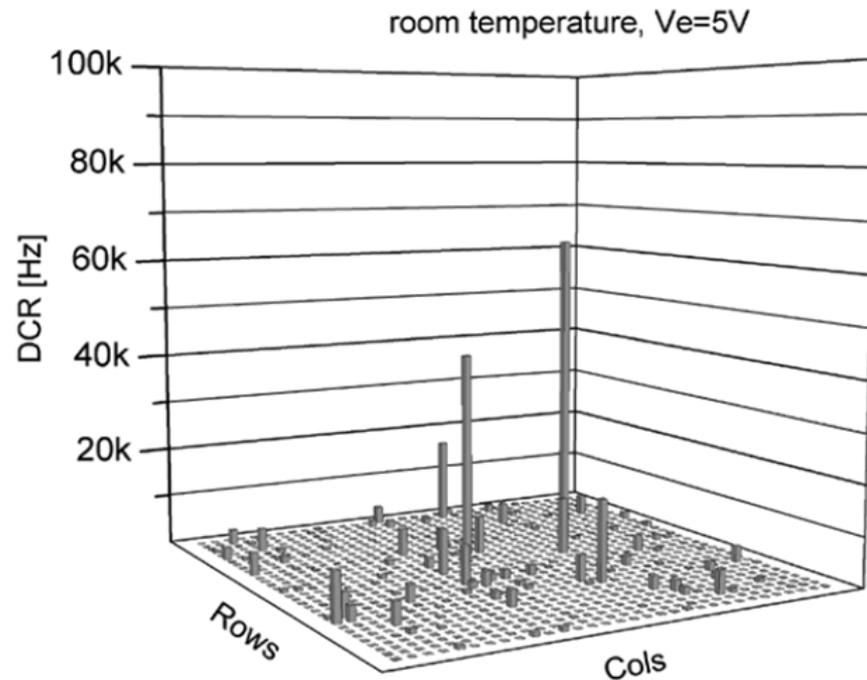
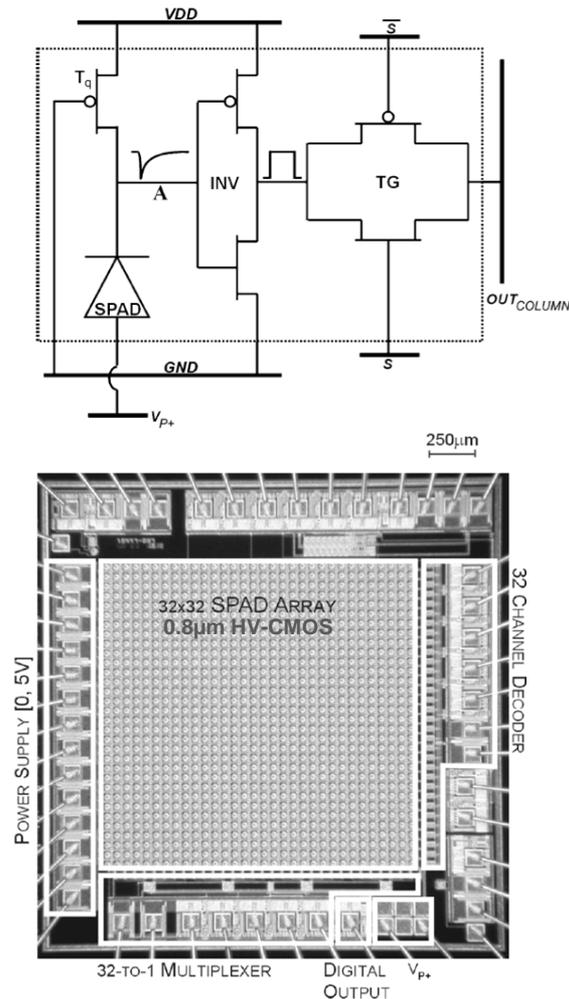
- The probability to detect a dark count is reduced by using short  $t_{obs}$ .



$DCR = \text{dark counts} \cdot t_{obs}$

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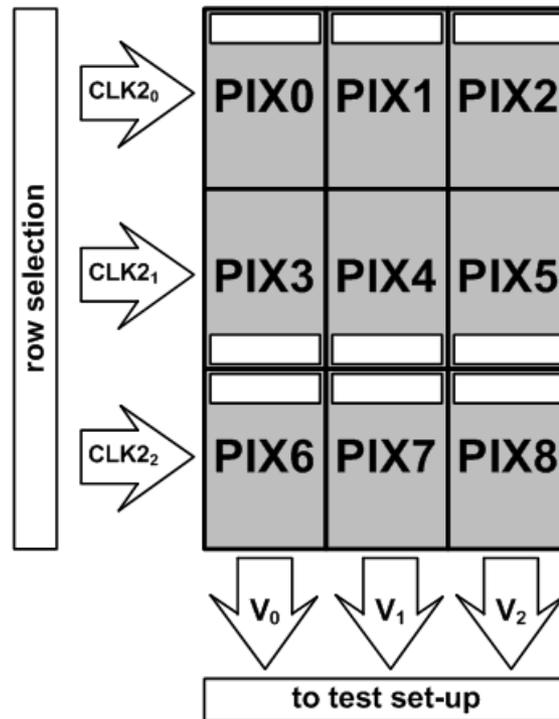
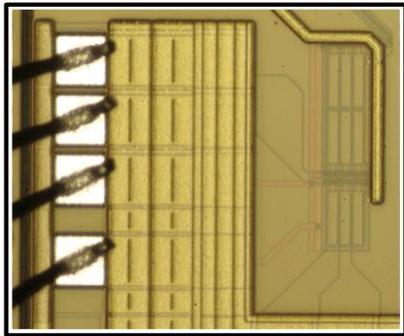
- Presence of dead pixels in GAPD arrays.



C. Niclass et al., "Design and characterization of a CMOS 3-D image sensor based on single photon avalanche diodes", IEEE Journal of Solid-State Circuits, vol. 40, no. 9, 2005.



- The gated operation is also effective in avoiding sensor blindness around a triggering signal in GAPD arrays.
  - 3 x 3 GAPD array.
  - Column parallel readout (CLK2 acts as a row selector).

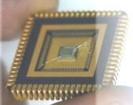


**Sensor blindness**  
No detection is possible

(a) $t_{obs}=10\mu s, n_{rep}=1$			(b) $t_{obs}=10ns, n_{rep}=1$			Dark counts
1	0	0	0	0	0	
1	1	1	0	0	0	
1	1	1	0	0	0	
1	1	1	0	0	0	

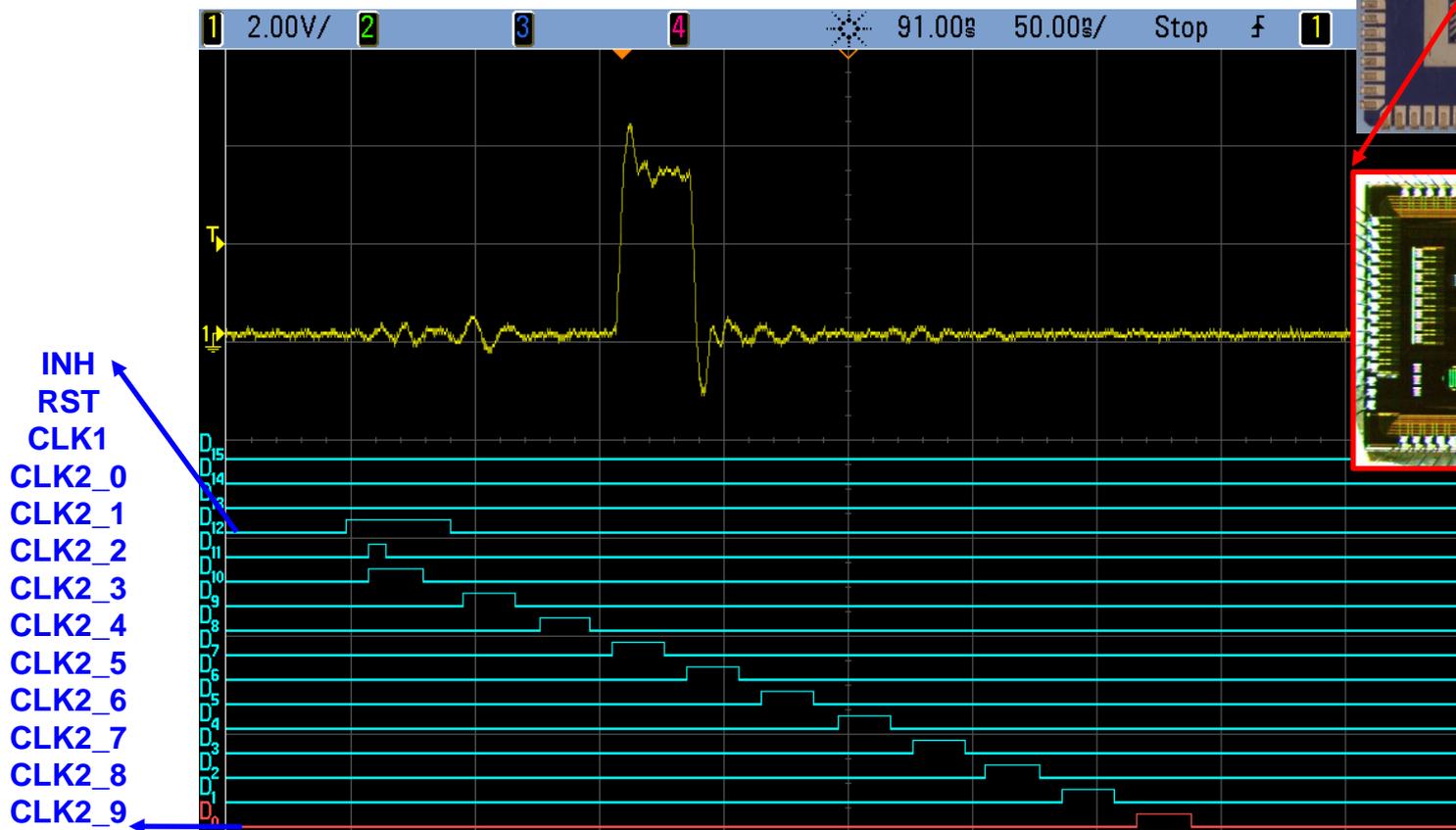
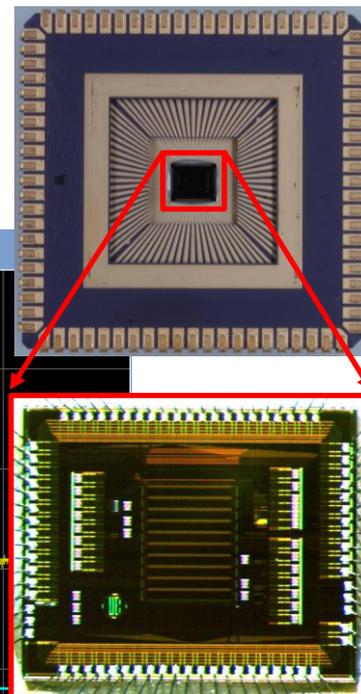
**Sensor ready for detection (short  $t_{obs}$ )**

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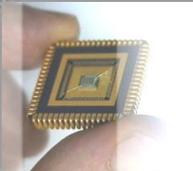
## ○ Preliminary results

- The GAPD array has shown signs of life... Observation of noise counts for one output channel.



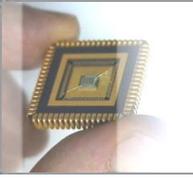
$t_{obs} = 7ns$   
 $V_{HV} = 20.7V$

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## ○ Conclusions

- We plan to test the efficiency of GAPDs fabricated with  $0.35\mu\text{m}$  HV-AMS technology in particle detection at 2 test beams very soon.
  - We expect to distinguish detection between neighbour pixels (DESY) and within one pixel (CERN).
- Given that we want to prove the efficiency of the sensor, some aspects have not been taken into account (fill-factor, radiation tolerance, best technology).
- The test set-up will be comprised of...
  - $1\text{mm} \times 1\text{mm}$  GAPD array, satellite electronics, scintillators, EUDET telescope and TLU.
- The GAPD array consists of...
  - Digital pixels with integrated readout.
  - $20\mu\text{m} \times 100\mu\text{m}$  sensors.
- The sensors are operated in the gated acquisition because...
  - Avoids afterpulses and reduces observed dark count.
  - Eliminates dead pixels.
  - Avoids sensor blindness.



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# Thank you for your attention

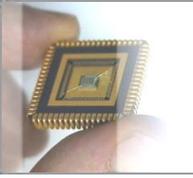
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Questions and comments are welcome

LCWS11  
Granada 26-30 September 2011



Department  
of Electronics  
Universitat de Barcelona



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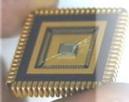
# Back-up slides

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Granada 26-30 September 2011

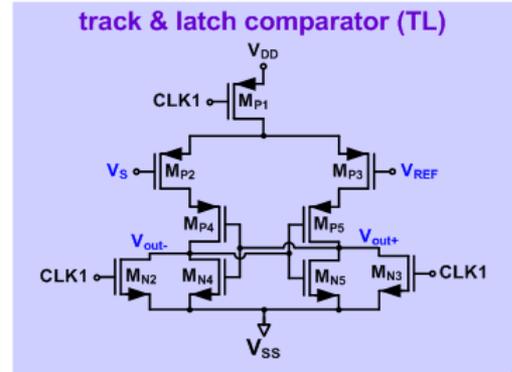
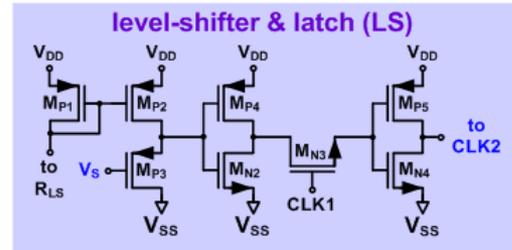
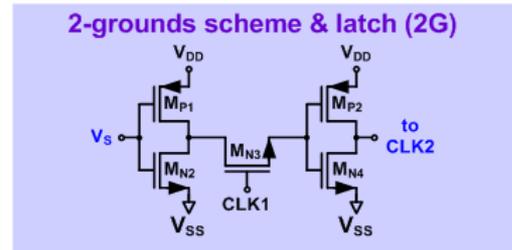
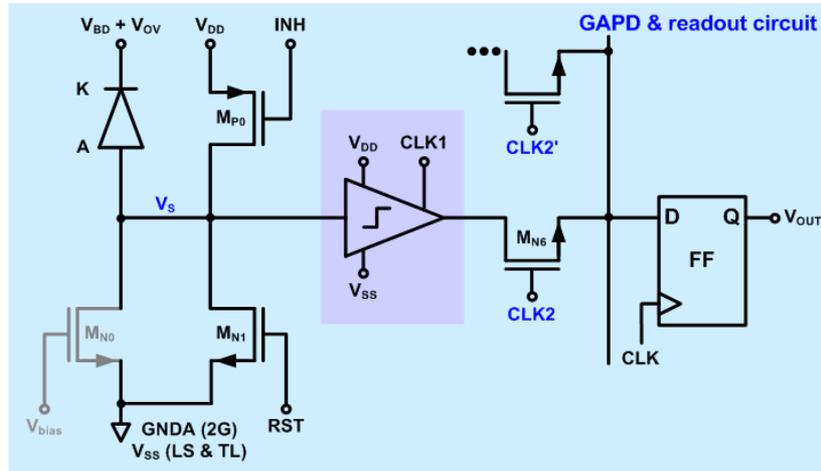
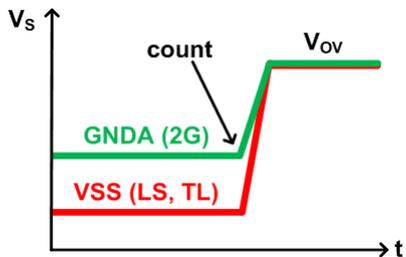
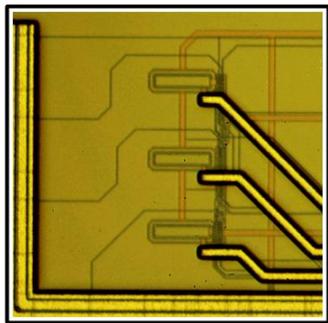


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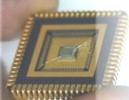


○ We developed readout circuits for low noise GAPD pixels

- Monolithically integrated with the sensor
- Comprised of electronics for gated operation **and 3 different readout circuits**
- Digital output

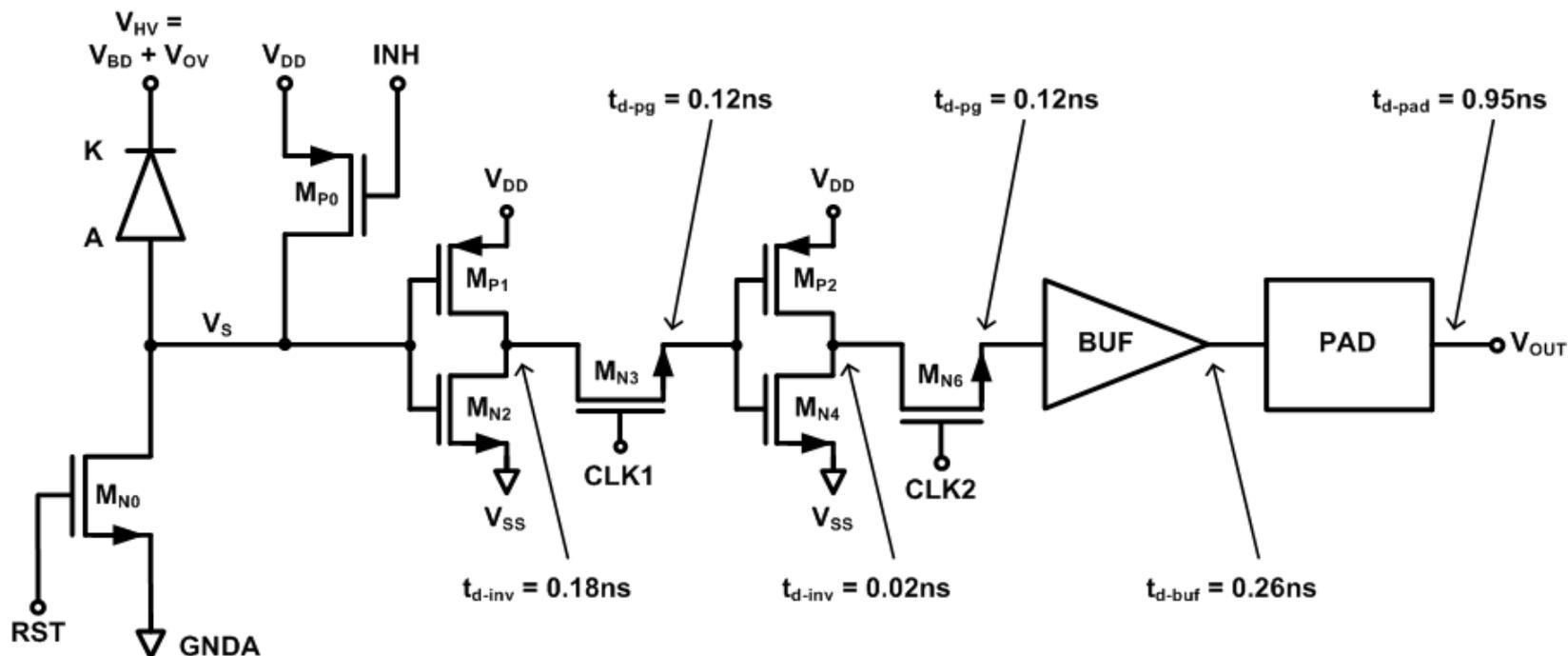


*E. Vitella*



## ○ Delay introduced by the electronics

- Total delay introduced by electronics is 1.65ns.



*E. Vitella*